



Material Content Data Sheet



Sales Product Name	TLE7469G V53			Issued	28. August 2013			
MA#	MA000616594							
Package	PG-DSO-12-11			Weight*	401.69 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.559	0.89	0.89	8860	8860
leadframe	non noble metal	iron	7439-89-6	0.230	0.06		574	
	inorganic material	phosphorus	7723-14-0	0.069	0.02		172	
	non noble metal	copper	7440-50-8	230.106	57.28	57.36	572851	573597
wire	non noble metal	aluminium	7429-90-5	0.155	0.04	0.04	386	386
encapsulation	organic material	carbon black	1333-86-4	0.316	0.08		788	
	plastics	epoxy resin	-	14.553	3.62		36231	
	inorganic material	silicondioxide	60676-86-0	143.319	35.68	39.38	356794	393813
leadfinish	non noble metal	tin	7440-31-5	4.235	1.05	1.05	10544	10544
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		4	
	non noble metal	nickel	7440-02-0	0.612	0.15	0.15	1524	1528
solder	noble metal	silver	7440-22-4	0.113	0.03		282	
	non noble metal	tin	7440-31-5	0.091	0.02		225	
	non noble metal	lead	7439-92-1	4.324	1.08	1.13	10765	11272
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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